

CLAIMS

What is claimed is:

1. A semiconductor package with a crack-preventing member, comprising:
 - a chip carrier;
 - at least a chip mounted on the chip carrier and electrical connected to the chip carrier;
 - at least a crack-preventing member formed at a predetermined position on the chip, for generating compression stress on the chip to counteract tension stress produced from the chip carrier on the chip in a molding process, so as to prevent the chip from cracking; and
 - an encapsulant for encapsulating the chip and the crack-preventing member.
2. The semiconductor package of claim 1, wherein the crack-preventing member is made of epoxy resin.
3. The semiconductor package of claim 1, wherein the crack-preventing member is dimensioned to be in one-third thickness of the chip.
4. The semiconductor package of claim 1, wherein the crack-preventing member is dimensionally larger than one third in thickness of the chip.
5. The semiconductor package of claim 1, wherein the crack-preventing member is dimensioned to be in half thickness of the chip.
6. The semiconductor package of claim 1, wherein the crack-preventing member is a resin dam structure.
7. The semiconductor package of claim 1, wherein the crack-preventing member is composed of two resin dam structures that are properly spaced apart from each other.

8. The semiconductor package of claim 1, wherein the crack-preventing member is composed of two intercrossed resin dam structures.
9. The semiconductor package of claim 1, wherein the crack-preventing member is composed of three intercrossed resin dam structures.
10. The semiconductor package of claim 1, wherein the crack-preventing member is a rectangular frame structure.
11. The semiconductor package of claim 1, wherein the crack-preventing member and the chip carrier are attached to opposing sides of the chip, respectively.
12. The semiconductor package of claim 1, wherein the chip carrier is a substrate.
13. The semiconductor package of claim 1, wherein the chip carrier is a lead frame.
14. The semiconductor package of claim 1, wherein the crack-preventing member is disposed on a top surface of the chip.
15. The semiconductor package of claim 1, wherein the crack-preventing member is disposed on a bottom surface of the chip.